

8

7

6

5

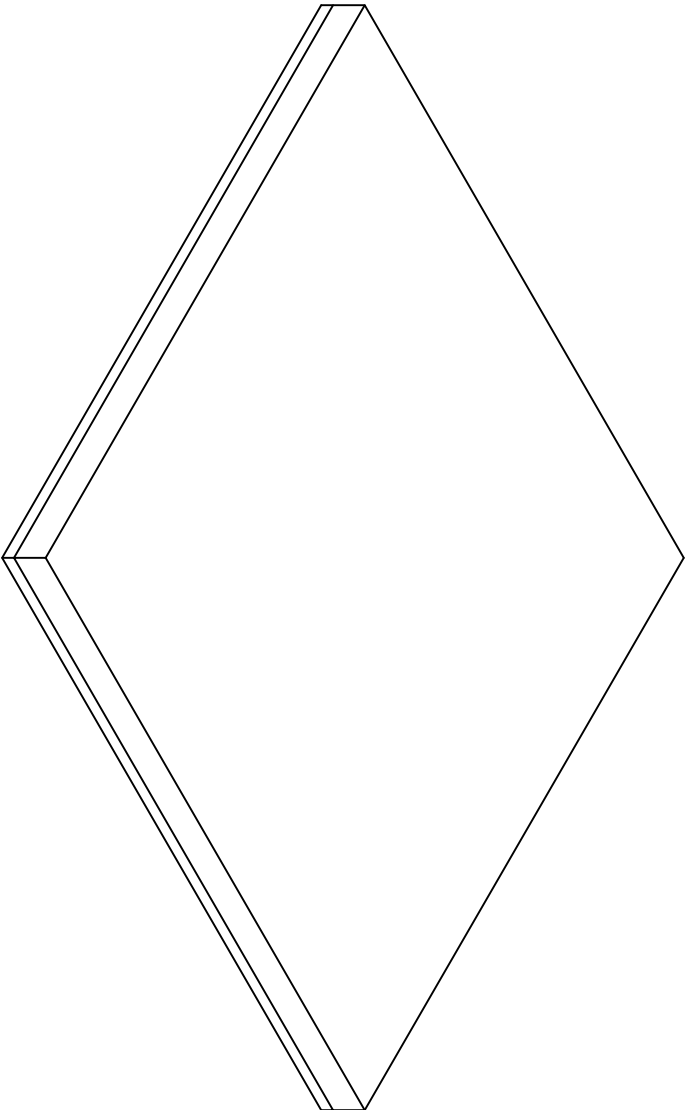
4

3

2

1

REVISION HISTORY				
REV	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	INITIAL RELEASE	WBBANG	WBBANG	04/07/08



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001–0531–2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001–0519–2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 484.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 22 X 22.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.65mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M–1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Anchor Technology, Inc. Chandler, Arizona, USA Anom Semiconductor, Inc., Seoul, Korea www.amkor.com			
DECIMAL X.X ±0.1 X.XX ±0.05 X.XXX ±0.030		ANGULAR ±1°		INTERPRET DIM AND TOL PER ASME Y14.5M – 1994			
MATERIAL		N/A		PRODUCT MANAGER			
FINISH		N/A		VP/ERE			
DO NOT SCALE DRAWING		SMSEO		RELEASED			
				04/07/08			
				03/28/08			
				WBANG			
				DESIGNED			
				03/28/08			
				APPROVALS			
				DATE			
				03/28/08			
				HJLEON			
				CHECKED			
				03/28/08			
				HJLEON			
				PRODUCT MANAGER			
				VP/ERE			
				03/28/08			
				RELEASED			
				SMSEO			
				04/07/08			
				WBANG			
				WBANG			
				04/07/08			
				INITIAL RELEASE			
				00			

7

6

5

4

3

2

1